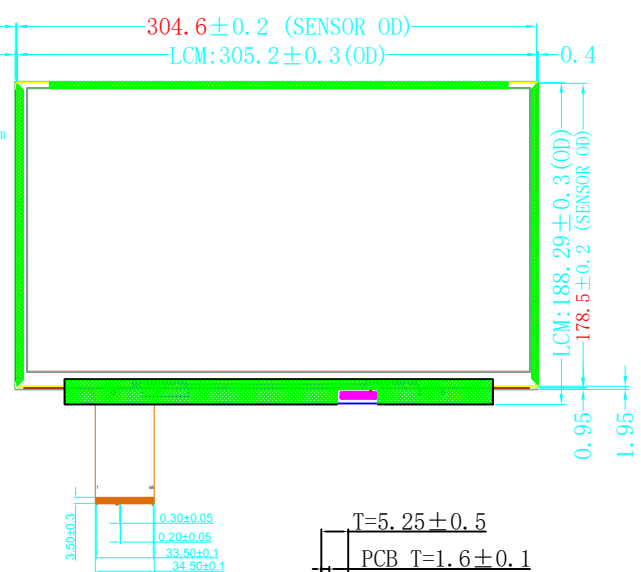
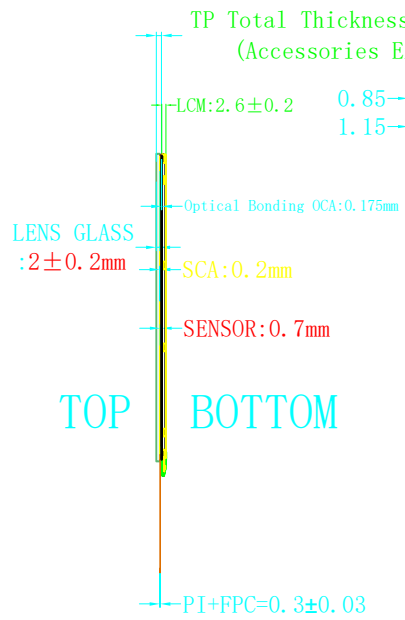
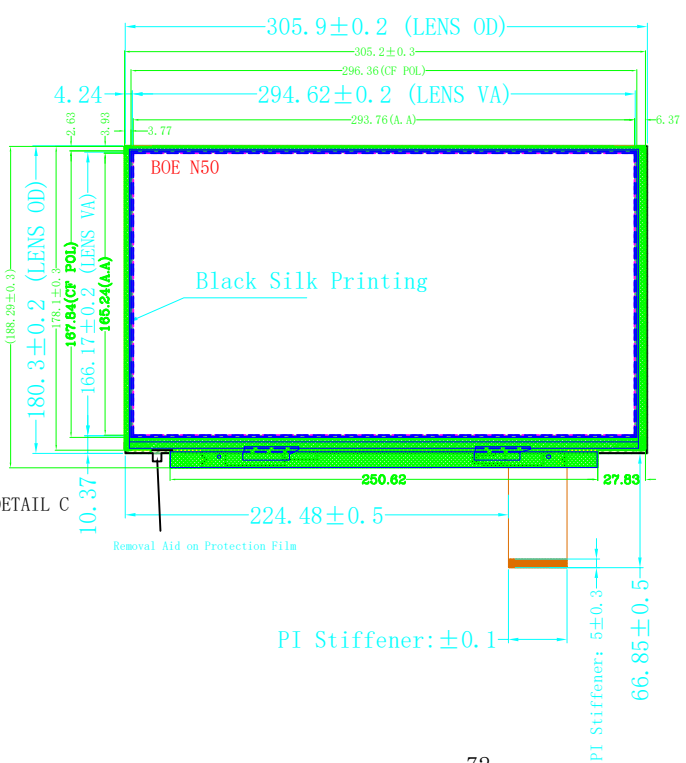


客户签名:
日期:

Front Viw

Side View

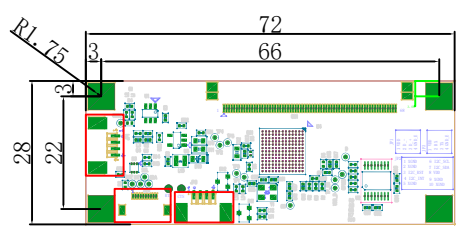
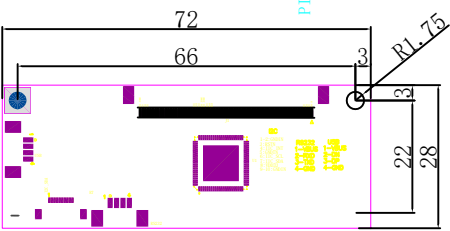
Back View



(G+G+LCM Structure)

T=5.25±0.5
PCB T=1.6±0.1
TP Connector T=1.8
Soldering T=0.15
USB T=3.5
IIC T=2

Technical Parameters:
1. GLASS+SCA+Glass ITO+FPC
2. COB IC: ILI2511MP.C2.P1.V1
3. Glass Cover: Asahi Glass
4. Transparency: ≥86%
5. Glass Cover Hardness: ≥6H
6. TP Operating Environment: -10°C~+60°C, ≤90%RH
7. TP Storage Environment: -20°C~+70°C, ≤90%RH
8. This product is ROHS compliant.
9. Unspecified Tolerance: ±0.2mm



ILI 12C Communication	
PIN	Definition
1	GND
2	GND
3	VDD
4	SDA
5	SCL
6	GND
7	INT
8	RST
9	GND
10	GND

J1 (USB Communication)	
PIN	Definition
1	VDD/5V
2	D-
3	D+
4	GND

EXC 12C Communication	
PIN	Definition
1	GND
2	GND
3	RST
4	INT
5	GND
6	SCL
7	SDA
8	VDD
9	GND
10	GND

物料	NO.	更改内容	日期
	1		
	2		
	3		
	4		
	5		
	6		
	7		

工程确认图

MAXEN ELECTRONICS LIMITED

方向

绘图 审核 日期

20211224

公司编号	MX-B133FE30-IS03KB-F1622	未注公差	±0.20
客户编号		单位	mm
版本号		比例	1 : 1